

TABLE OF CONTENTS

Specifications.....	3	Applications Information	13
Timing Specifications.....	4	Differential Data Transmission	13
Absolute Maximum Ratings.....	5	Cable and Data Rate.....	13
ESD Caution.....	5	Thermal Shutdown	13
Pin Configuration and Function Descriptions.....	6	Propagation Delay	13
Test Circuits.....	7	Receiver Open-Circuit Fail-Safe.....	13
Switching Characteristics	8	Outline Dimensions	15
Typical Performance Characteristics	9	Ordering Guide	15

REVISION HISTORY

3/05—Rev. 0 to Rev. A	
Updated Format.....	Universal
Added PROFIBUS Logo	1
Updated Outline Dimensions	15
Changes to Ordering Guide	15

11/02—Revision 0: Initial Version

SPECIFICATIONS

$V_{CC} = 5\text{ V} \pm 5\%$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 1.

Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER					
Differential Output Voltage, V_{OD}			5.0	V	$R = \text{Infinity}$, see Figure 3
	2.1		5.0	V	$V_{CC} = 5\text{ V}$, $R = 50\ \Omega$ (RS-422), see Figure 3
	2.1		5.0	V	$R = 27\ \Omega$ (RS-485), see Figure 3
V_{OD3}	2.1		5.0	V	$V_{TST} = -7\text{ V}$ to $+12\text{ V}$, see Figure 4
$\Delta V_{OD} $ for Complementary Output States			0.2	V	$R = 27\ \Omega$ or $50\ \Omega$, see Figure 3
Common-Mode Output Voltage V_{OC}			3.0	V	$R = 27\ \Omega$ or $50\ \Omega$, see Figure 3
$\Delta V_{OC} $ for Complementary Output States			0.2	V	$R = 27\ \Omega$ or $50\ \Omega$
Output Short-Circuit Current ($V_{OUT} = \text{High}$)	60		200	mA	$-7\text{ V} \leq V_O \leq +12\text{ V}$
Output Short-Circuit Current ($V_{OUT} = \text{Low}$)	60		200	mA	$-7\text{ V} \leq V_O \leq +12\text{ V}$
CMOS Input Logic Threshold Low, V_{INL}			0.8	V	
CMOS Input Logic Threshold High, V_{INH}	2.0			V	
Logic Input Current (DE, DI)			± 1.0	μA	
RECEIVER					
Differential Input Threshold Voltage, V_{TH}	-0.2		+0.2	V	$-7\text{ V} \leq V_{CM} \leq +12\text{ V}$
Input Voltage Hysteresis, ΔV_{TH}		70		mV	$V_{CM} = 0\text{ V}$
Input Resistance	20	30		k Ω	$-7\text{ V} \leq V_{CM} \leq +12\text{ V}$
Input Current (A, B)			0.6	mA	$V_{IN} = +12\text{ V}$
			-0.35	mA	$V_{IN} = -7\text{ V}$
Logic Enable Input Current ($\overline{RE}$)			± 1.0	μA	
CMOS Output Voltage Low, V_{OL}			0.4	V	$I_{OUT} = +4.0\text{ mA}$
CMOS Output Voltage High, V_{OH}	4.0			V	$I_{OUT} = -4.0\text{ mA}$
Short-Circuit Output Current	7		85	mA	$V_{OUT} = \text{GND}$ or V_{CC}
Three-State Output Leakage Current			± 1.0	μA	$0.4\text{ V} \leq V_{OUT} \leq 2.4\text{ V}$
POWER SUPPLY CURRENT					
I_{CC} (Outputs Enabled)		1.2	2.0	mA	Outputs unloaded, digital inputs = GND or V_{CC}
I_{CC} (Outputs Disabled)		0.8	1.5	mA	Outputs unloaded, digital inputs = GND or V_{CC}

TIMING SPECIFICATIONS

$V_{CC} = 5\text{ V} \pm 5\%$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 2.

Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER					
Propagation Delay Input to Output t_{PLH} , t_{PHL}	4	11	17	ns	$R_{LDIFF} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\text{ pF}$, see Figure 5
		11	13	ns	$R_{LDIFF} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\text{ pF}$ @ $T_A = 25^\circ\text{C}$
Driver O/P to $\overline{O/P}$ t_{SKEW}		0.5	2	ns	$R_{LDIFF} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\text{ pF}$, see Figure 5 ¹
Driver Rise/Fall Time t_R , t_F		8	15	ns	$R_{LDIFF} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\text{ pF}$, see Figure 5
Driver Enable to Output Valid t_{ZH} , t_{ZL}		9	15	ns	$R_L = 110\ \Omega$, $C_L = 50\text{ pF}$, see Figure 6
Driver Disable Timing t_{HZ} , t_{LZ}		9	15	ns	$R_L = 110\ \Omega$, $C_L = 50\text{ pF}$, see Figure 6
Matched Enable Switching $ t_{AZH} - t_{BZL} $, $ t_{BZH} - t_{AZL} $		1	3	ns	$R_L = 110\ \Omega$, $C_L = 50\text{ pF}$, see Figure 6
Matched Disable Switching $ t_{AHZ} - t_{BLZ} $, $ t_{BHZ} - t_{ALZ} $		2	5	ns	$R_L = 110\ \Omega$, $C_L = 50\text{ pF}$, see Figure 6
RECEIVER					
Propagation Delay Input to Output t_{PLH} , t_{PHL}	6	12	20	ns	$C_L = 15\text{ pF}$, see Figure 7
Skew $ t_{PLH} - t_{PHL} $		0.4	2	ns	$C_L = 15\text{ pF}$ ¹ , see Figure 7
Receiver Enable t_{ZH} , t_{ZL}		7	13	ns	$C_L = 15\text{ pF}$, $R_L = 1\text{ k}\Omega$, see Figure 8
Receiver Disable t_{HZ} , t_{LZ}		7	13	ns	$C_L = 15\text{ pF}$, $R_L = 1\text{ k}\Omega$, see Figure 8

¹ Guaranteed by characterization.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 3.

Parameter	Rating
V_{CC}	7 V
Inputs	
Driver Input (DI)	$-0.3\text{ V to }V_{CC} + 0.3\text{ V}$
Control Inputs (DE, $\overline{RE}$)	$-0.3\text{ V to }V_{CC} + 0.3\text{ V}$
Receiver Inputs (A, B)	$-9\text{ V to }+14\text{ V}$
Outputs	
Driver Outputs	$-9\text{ V to }+14\text{ V}$
Receiver Outputs	$-0.5\text{ V to }V_{CC} + 0.5\text{ V}$
Power Dissipation 8-Lead SOIC	450 mW
θ_{JA} , Thermal Impedance	170°C/W
Operating Temperature Range	
Industrial (A Version)	$-40^\circ\text{C to }+85^\circ\text{C}$
Storage Temperature Range	$-65^\circ\text{C to }+150^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)	300°C
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



ADM1486

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

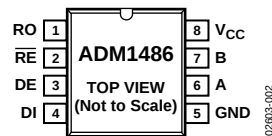


Figure 2. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	RO	Receiver Output. When enabled, if $A > B$ by 200 mV, RO = high. If $A < B$ by 200 mV, RO = low.
2	$\overline{RE}$	Receiver Output Enable. A low level enables the receiver output, RO. A high level places it in a high impedance state.
3	DE	Driver Output Enable. A high level enables the driver differential outputs, A and B. A low level places it in a high impedance state.
4	DI	Driver Input. When the driver is enabled, a logic low on DI forces A low and B high, while a logic high on DI forces A high and B low.
5	GND	Ground Connection, 0 V.
6	A	Noninverting Receiver Input A/Driver Output A.
7	B	Inverting Receiver Input B/Driver Output B.
8	V _{CC}	Power Supply, 5 V $\pm 5\%$.

Table 5. Transmitting

DE Input	DI Input	B Output	A Output
1	1	0	1
1	0	1	0
0	X	Z	Z

Table 6. Receiving

$\overline{RE}$	A-B Input	RO Output
0	$\geq +0.2$ V	1
0	≤ -0.2 V	0
0	Inputs open	1
1	X	Z

TEST CIRCUITS

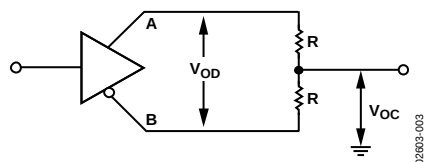


Figure 3. Driver Voltage Measurement

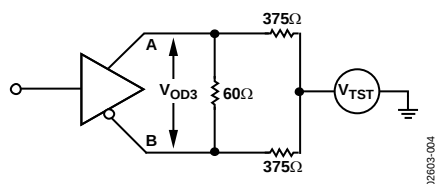


Figure 4. Driver Voltage Measurement

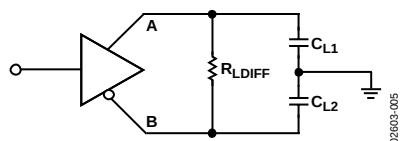


Figure 5. Driver Propagation Delay

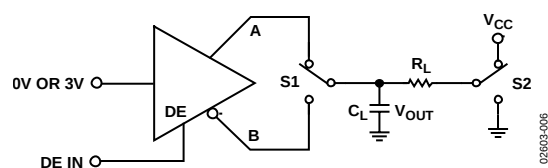


Figure 6. Driver Enable/Disable

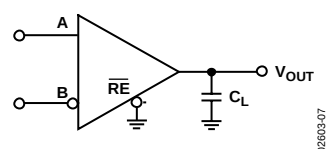


Figure 7. Receiver Propagation Delay

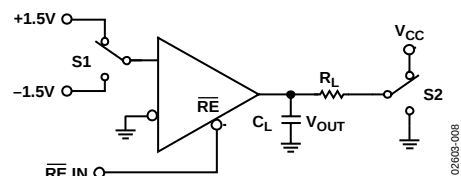


Figure 8. Receiver Enable/Disable

SWITCHING CHARACTERISTICS

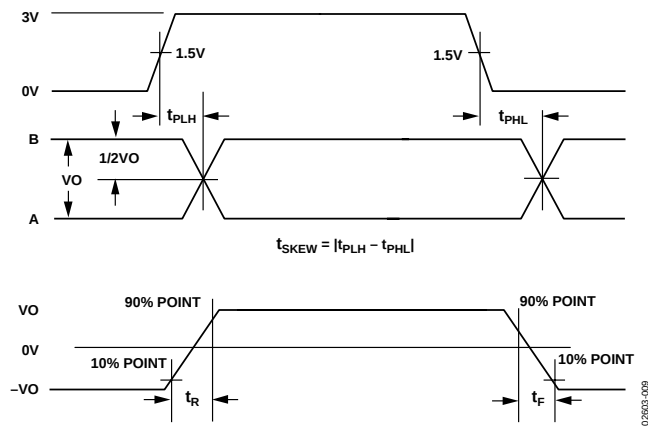


Figure 9. Driver Propagation Delay, Rise/Fall Timing

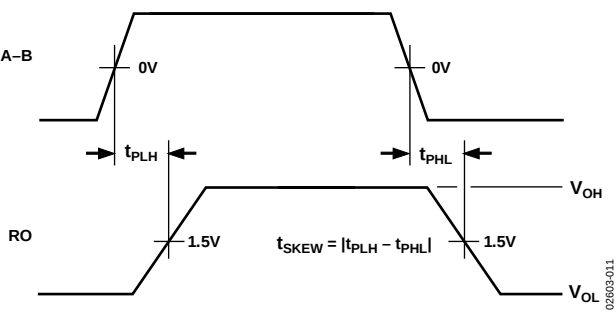


Figure 11. Receiver Propagation Delay

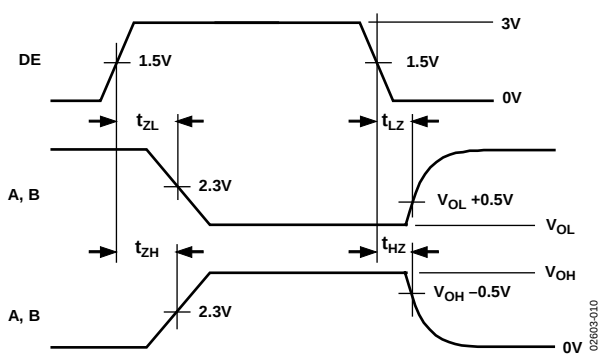


Figure 10. Driver Enable/Disable Timing

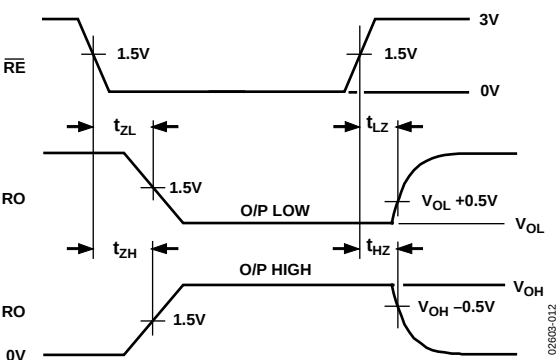


Figure 12. Receiver Enable/Disable Timing

TYPICAL PERFORMANCE CHARACTERISTICS

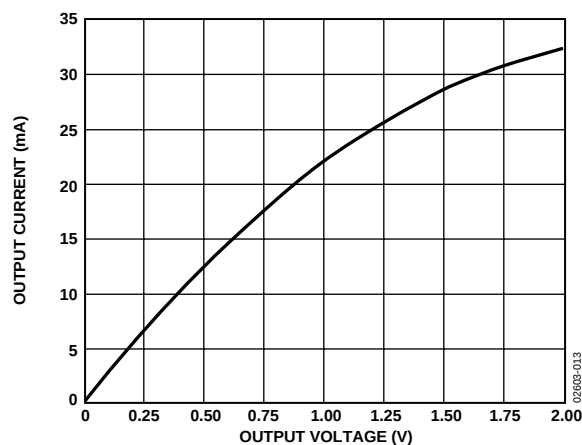


Figure 13. Output Current vs. Receiver Output Low Voltage

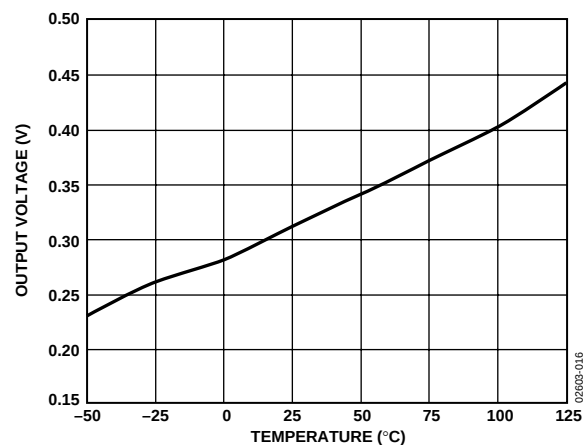
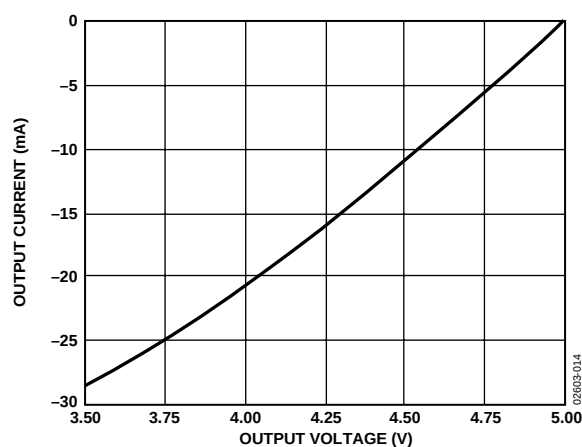
Figure 16. Receiver Output Low Voltage vs. Temperature
($I = 8$ mA)

Figure 14. Output Current vs. Receiver Output High Voltage

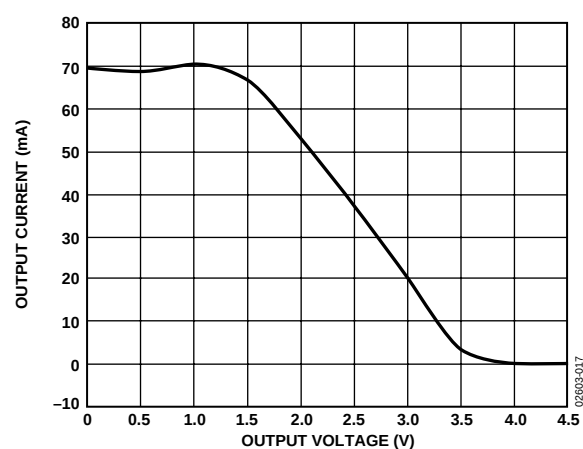
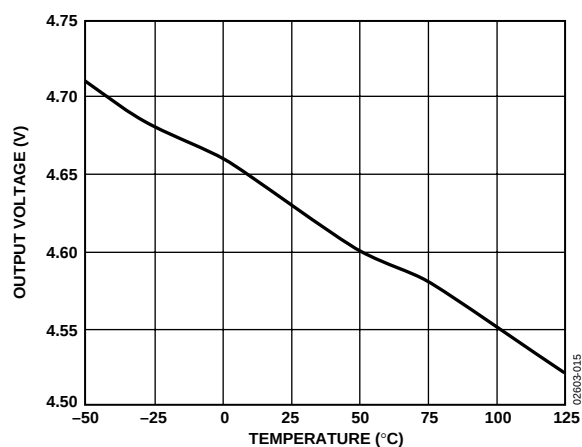
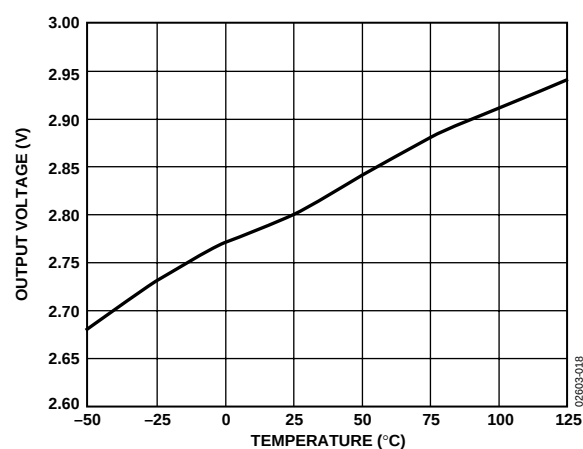


Figure 17. Output Current vs. Driver Differential Output Voltage

Figure 15. Receiver Output High Voltage vs. Temperature
($I = 8$ mA)Figure 18. Driver Differential Output Voltage vs. Temperature
($R_{L\text{DIFF}} = 53.6 \Omega$)

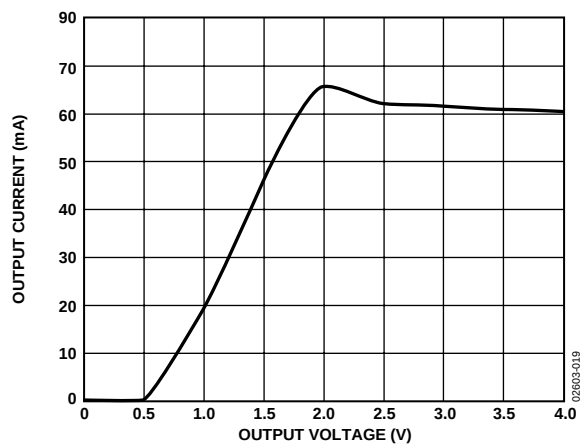


Figure 19. Output Current vs. Driver Output Low Voltage

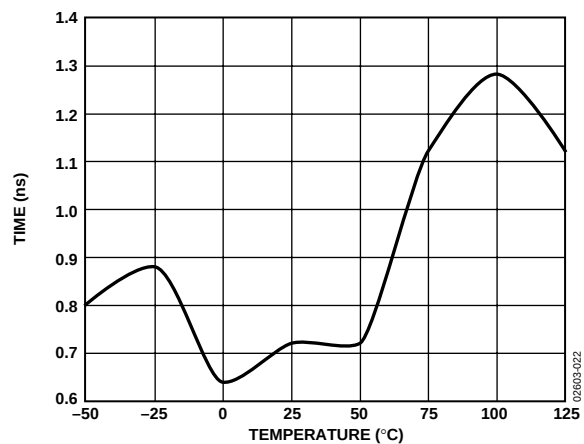


Figure 22. Receiver Skew vs. Temperature

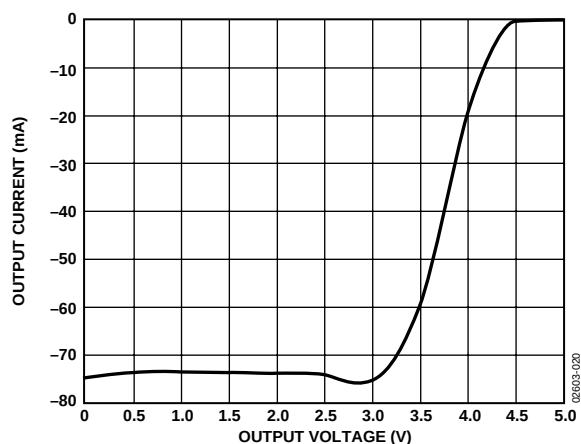


Figure 20. Output Current vs. Driver Output High Voltage

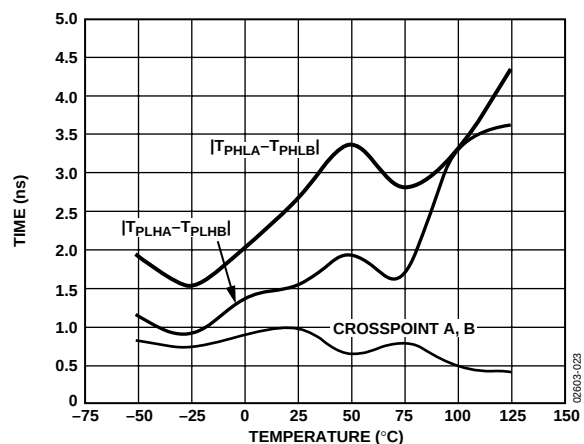


Figure 23. Driver Skew vs. Temperature

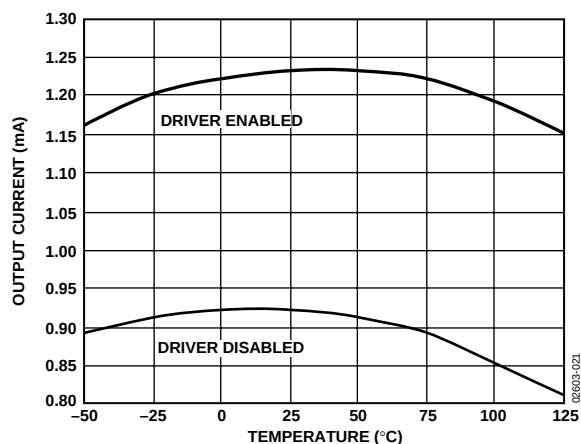


Figure 21. Supply Current vs. Temperature

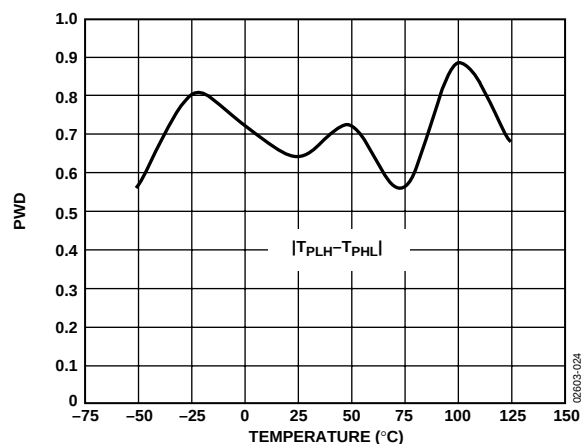


Figure 24. Tx Pulse Width Distortion

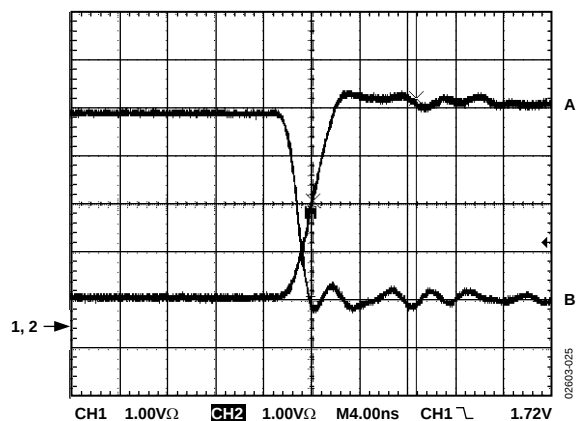


Figure 25. Unloaded Driver Differential Outputs

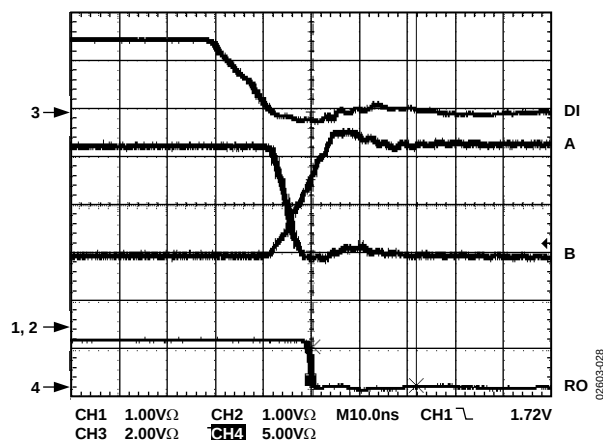


Figure 28. Driver/Receiver Propagation Delays High to Low ($R_{L\text{Diff}} = 54\Omega$, $C_{L1} = C_{L2} = 100\text{pF}$)

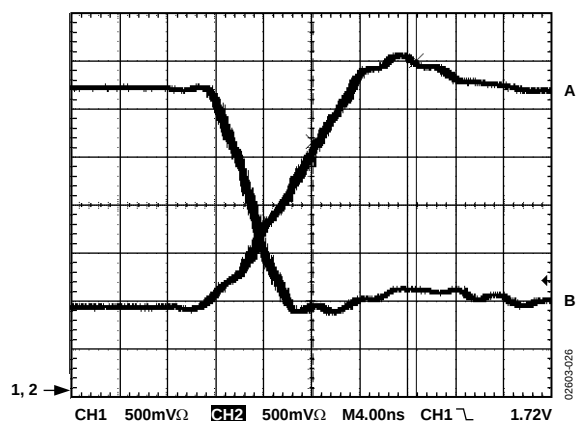


Figure 26. Loaded Driver Differential Output ($R_{L\text{Diff}} = 54\Omega$, $C_{L1} = C_{L2} = 100\text{pF}$)

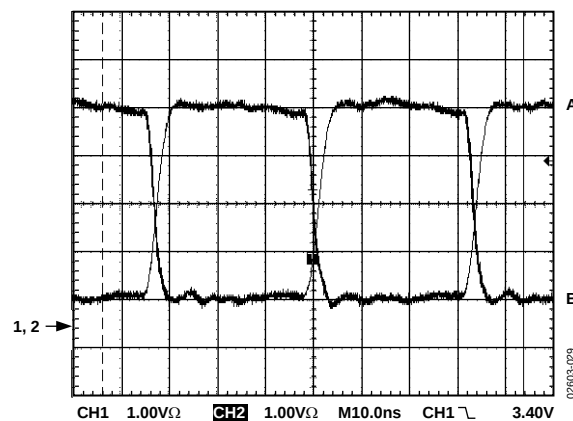


Figure 29. Unloaded Driver Outputs at 15 Mbps

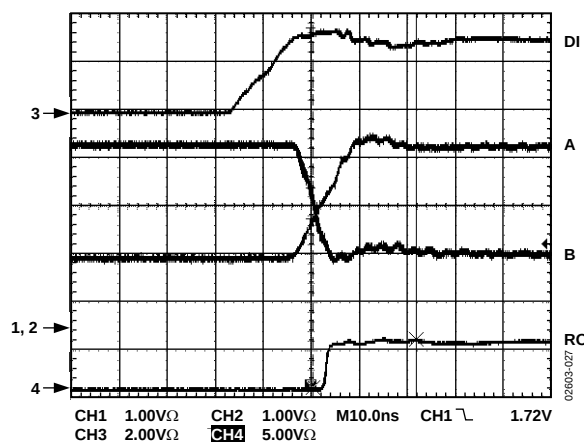


Figure 27. Driver/Receiver Propagation Delays Low to High ($R_{L\text{Diff}} = 54\Omega$, $C_{L1} = C_{L2} = 100\text{pF}$)

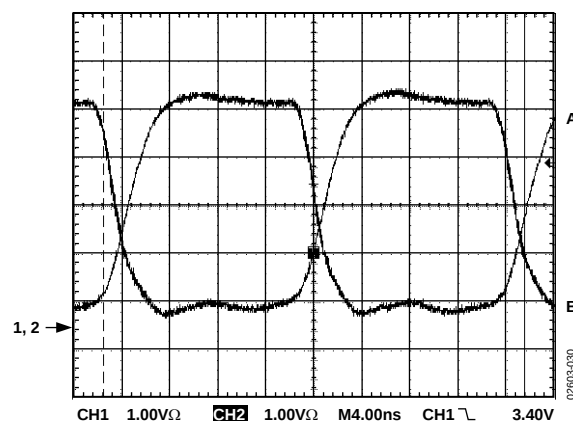


Figure 30. Unloaded Driver Outputs at 30 Mbps

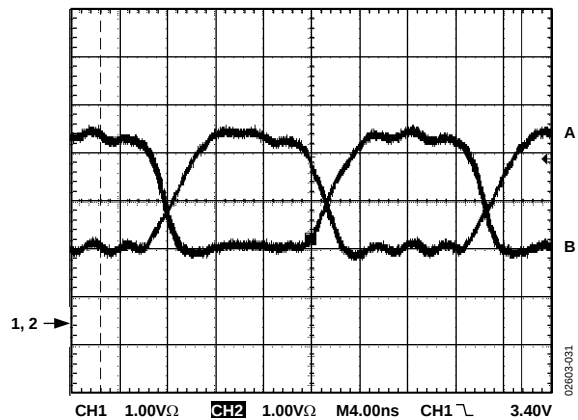


Figure 31. Loaded Driver Outputs at 15 Mbps
($R_{L\text{DIFF}} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\ \text{pF}$)

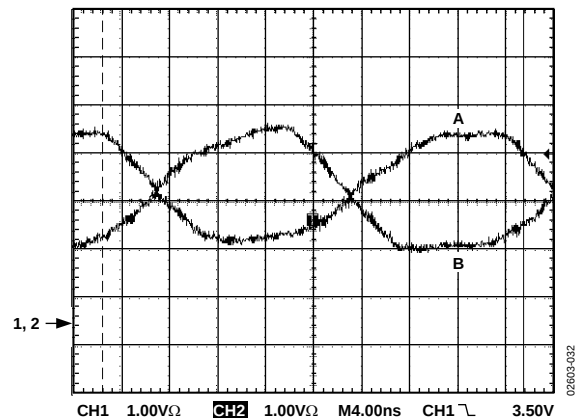


Figure 32. Loaded Driver Outputs at 30 Mbps
($R_{L\text{DIFF}} = 54\ \Omega$, $C_{L1} = C_{L2} = 100\ \text{pF}$)

APPLICATIONS INFORMATION

DIFFERENTIAL DATA TRANSMISSION

Differential data transmission is used to reliably transmit data at high rates over long distances and through noisy environments. Differential transmission nullifies the effects of ground shifts and noise signals that appear as common-mode voltages on the line. There are two main standards approved by the Electronics Industries Association (EIA) that specify the electrical characteristics of transceivers used in differential data transmission.

The RS-422 standard specifies data rates up to 10 MBaud and line lengths up to 4,000 feet. A single driver can drive a transmission line with up to 10 receivers.

In order to address true multipoint communications, the RS-485 standard was defined. This standard meets or exceeds all of the requirements of RS-422, and it allows up to 32 drivers and 32 receivers to connect to a single bus. An extended common-mode range of -7 V to $+12\text{ V}$ is defined. The most significant difference between the RS-422 and the RS-485 is that the drivers with RS-485 can be disabled, allowing more than one driver to be connected to a single line; in fact, 32 drivers can be connected to a single line. Only one driver should be enabled at a time, but the RS-485 standard contains additional specifications to guarantee device safety in the event of line contention.

CABLE AND DATA RATE

Twisted pair is the transmission line of choice for RS-485 communications. Twisted pair cable tends to cancel common-mode noise and causes cancellation of the magnetic fields generated by the current flowing through each wire, thereby reducing the effective inductance of the pair.

The ADM1486 is designed for bidirectional data communications on multipoint transmission lines. A typical application showing a multipoint transmission network is shown in Figure 33.

An RS-485 transmission line can have as many as 32 transceivers on the bus. Only one driver can transmit at a time, but multiple receivers may be enabled simultaneously.

As with any transmission line, it is important to minimize reflections. This can be achieved by terminating the extreme ends of the line using resistors equal to the characteristic impedance of the line. Stub lengths of the main line should also be kept as short as possible. A properly terminated transmission line appears purely resistive to the driver.

THERMAL SHUTDOWN

The ADM1486 contains thermal shutdown circuitry that protects the part from excessive power dissipation during fault conditions. Shorting the driver outputs to a low impedance source can result in high driver currents. Thermal sensing circuitry detects the increase in die temperature and disables the driver outputs. Thermal sensing circuitry is designed to disable the driver outputs when a die temperature reaches 150°C . As the device cools, the drivers are re-enabled at 140°C .

PROPAGATION DELAY

The ADM1486 features very low propagation delay, ensuring maximum baud rate operation. The well-balanced driver ensures distortion-free transmission.

Another important specification is a measure of the skew between the complementary outputs. Excessive skew impairs the noise immunity of the system and increases the amount of electromagnetic interference (EMI).

RECEIVER OPEN-CIRCUIT FAIL-SAFE

The receiver input includes a fail-safe feature that guarantees a logic high on the receiver when the inputs are open circuit or floating.

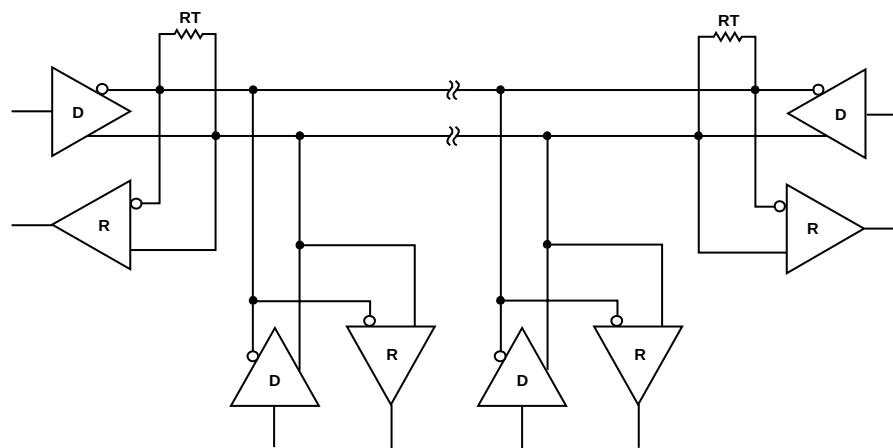


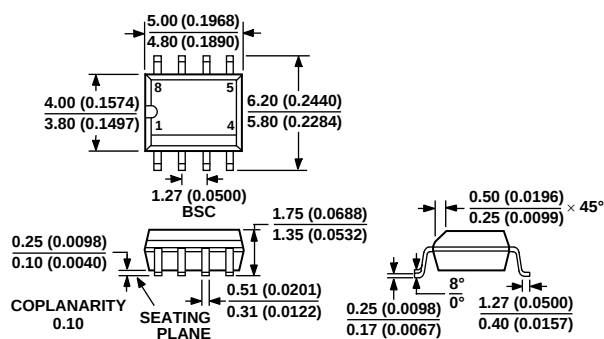
Figure 33. Typical RS-485 Network

ADM1486

Table 7. Comparison of RS-422, RS-485, and PROFIBUS Interface Standards

Specification	RS-422	RS-485	PROFIBUS
Transmission Type	Differential	Differential	Differential
Maximum Cable Length	4,000 ft.	4,000 ft.	
Minimum Driver Output Voltage	± 2 V	± 1.5 V	± 2.1 V
Driver Load Impedance	100 Ω	54 Ω	54 Ω
Receiver Input Resistance	4 k Ω min	12 k Ω min	20 k Ω min
Receiver Input Sensitivity	± 200 mV	± 200 mV	± 200 mV
Receiver Input Voltage Range	-7 V to +7 V	-7 V to +12 V	-7 V to +12 V
No. of Drivers/Receivers per Line	1/10	32/32	50/50

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-012AA
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

Figure 34. 8-Lead Standard Small Outline Package [SOIC]
Narrow Body
(R-8)

Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option
ADM1486AR	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8
ADM1486AR-REEL	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8
ADM1486AR-REEL7	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8
ADM1486ARZ ¹	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8
ADM1486ARZ-REEL ¹	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8
ADM1486ARZ-REEL7 ¹	−40°C to +85°C	8-Lead Narrow Body (SOIC)	R-8

¹ Z = Pb-free part.

ADM1486

NOTES